



imt

Innovative Manufacturing Technology Co.,Ltd.

Dry Cleaning Techniques

Focused on Semiconductor & OLED applications

2006. 5

,

www.imt-c.co.kr



Dry Cleaning Techniques

- Limits of wet cleaning
 - > High aspect ratio structure (contact, trench)
 - > Water mark
 - > Corrosion issues (Cu, low-k)
 - > Cluster tool
 - > Environmental issues (water, chemicals)

- Plasma cleaning
- Dry ice cleaning
- Ar aerosol cleaning
- UV lamp cleaning
- Super critical fluid cleaning
- Laser cleaning
- Laser shock cleaning
- Laser plasma cleaning

Plasma cleaning (1)

□ Remote plasma cleaning

- > Ashing = PR stripping
- > in-situ etch/strip processing

□ Direct plasma cleaning : Reactive plasma & Ar plasma

- > Ar plasma: pre-deposition cleaning by sputtering
- > Reactive plasma:

chemical reaction

=> volatile

byproducts

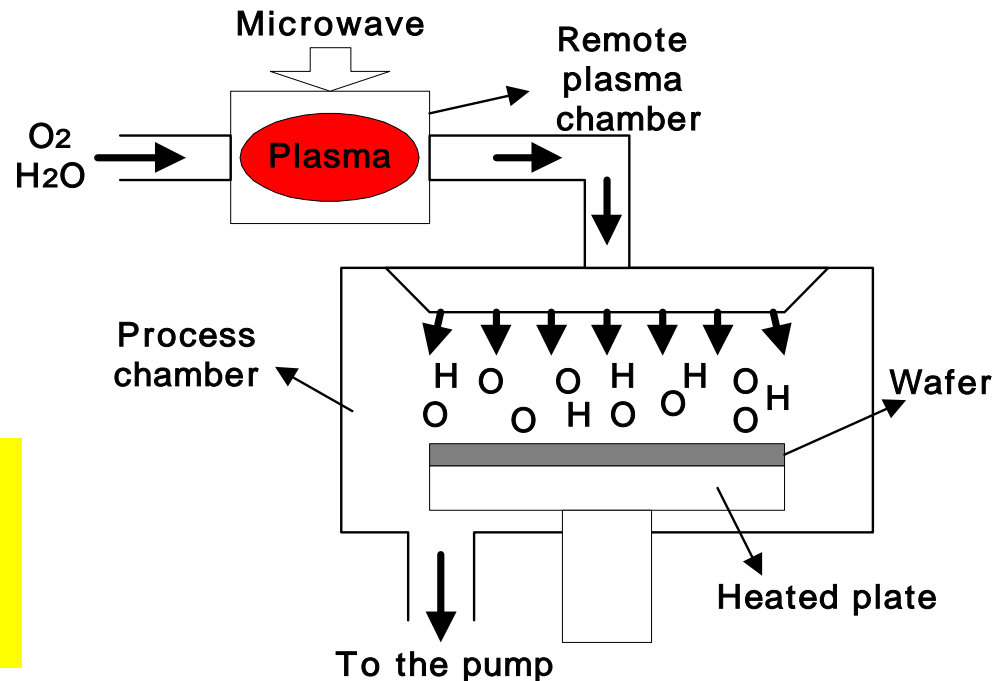
ex) PCB flux cleaning,
desmearing,
deflashing

*PR Stripping mechanism

: chemical reaction

➤ $O_2 \Rightarrow O+O$, $H_2O \Rightarrow 2H+O$

➤ $O + PR \Rightarrow H_2O+CO+CO_2 + \dots$



Plasma cleaning (2)

*Unique Characteristics

>> Advantages:

- 1) In-situ dry cleaning
- 2) No moisture effect => no metal corrosion
- 3) Good organic removal
- 4) Surface activation => good bond ability

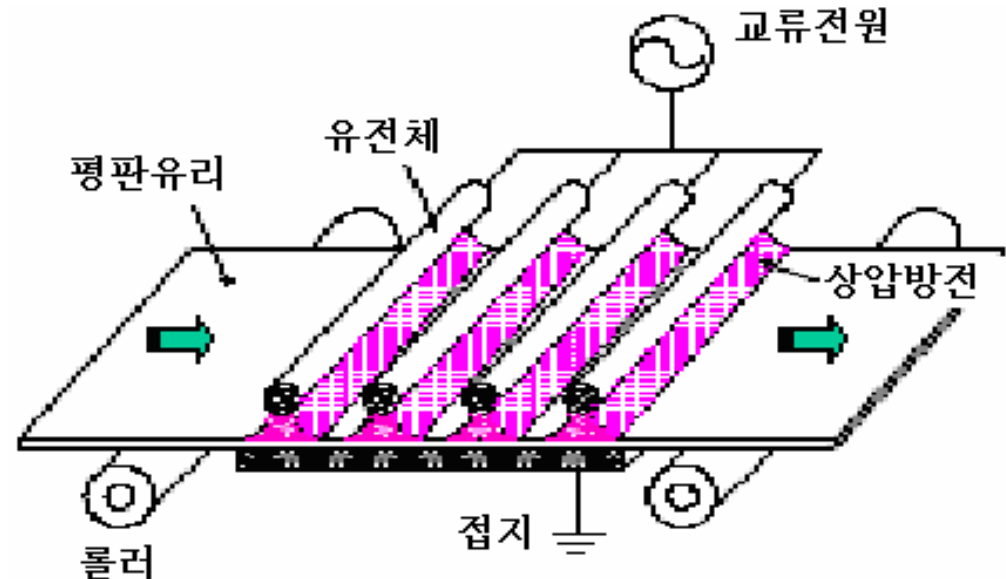
>> Disadvantages:

- 1) poor inorganic & strong PR residue removal
- 2) Isotropic cleaning
- 3) Plasma charging
- 4) Non-feasible double-side cleaning

□ Atmospheric Plasma cleaning

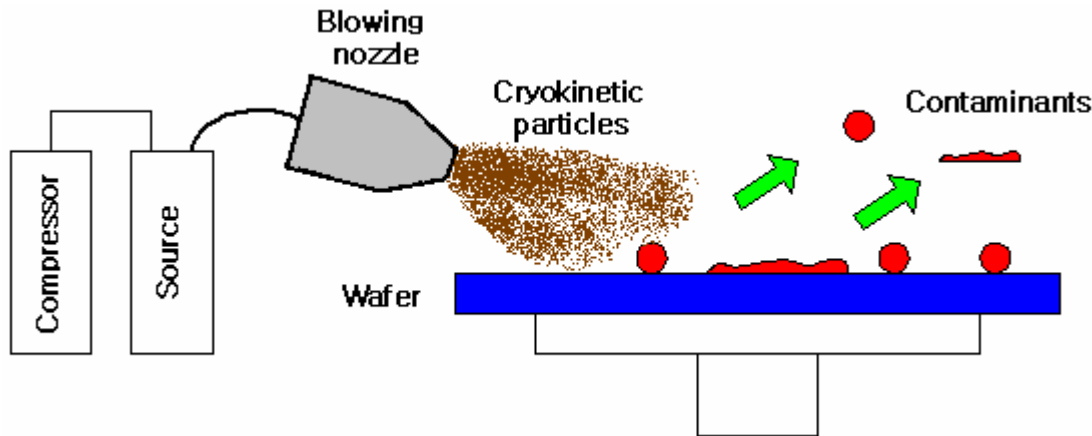
- > No vacuum
- > Conveyer system
- > Mass cleaning
- > Only flat surfaces

*Appl: FPD glass, pre-wiring & molding



Dry Ice cleaning (1)

- Cryokinetic source: CO₂

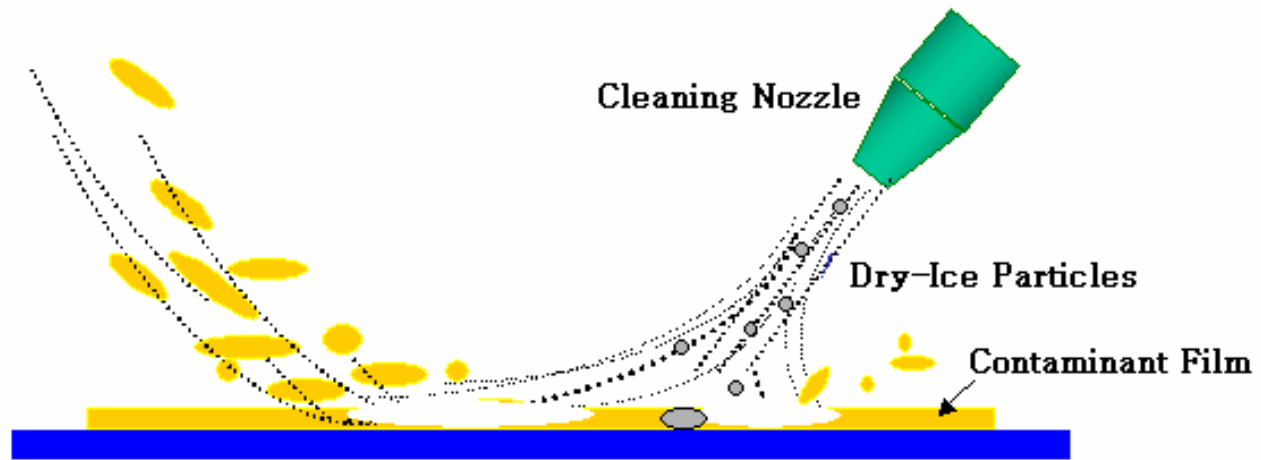


>> CO₂ dry ice pellets

>> Cleaning type

1. Soft dry ice cleaning = CO₂ snow cleaning
 - > liquid CO₂ => adiabatic expansion at nozzle => dry ice generation and blowing
2. Hard dry ice cleaning = CO₂ pellet cleaning
 - > Dry ice lump => pellet => high pressure blasting

Dry Ice cleaning (2)



Source: KCTech

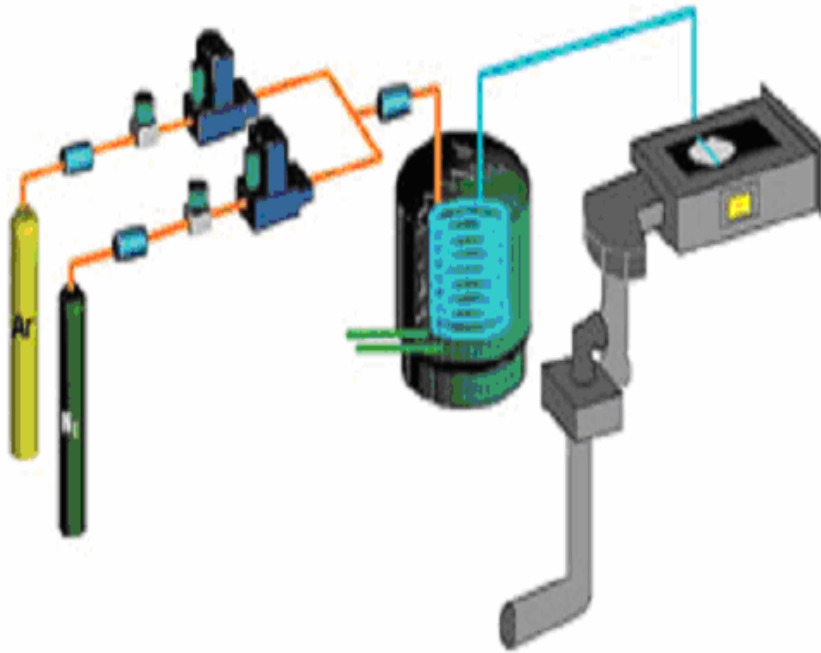
- Cleaning mechanisms
 - > Physical blasting
 - > Thermal shock (-78.7C)
 - > Sublimation expansion (x800)
 - > CO2 solubility: organic removal

- Applications
 - > Pellet : semi. equipment surface cleaning (Komico)
 - > Snow : FPD surface cleaning (KCTech)

Ar aerosol cleaning (1)

- Cryokinetic source: Ar
- Ar / N₂ mixture => compression => adiabatic expansion from the nozzle => Ar aerosol ejection

Argon and nitrogen are blended precisely → The mixture is precooled → Expansion forms argon-nitrogen crystals



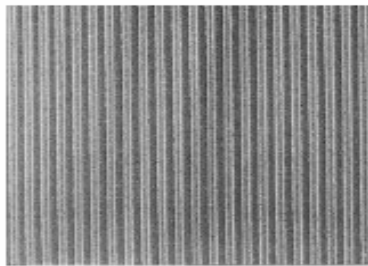
>> IBM patent technology => FSI International commercialized.

- **Advantages**
 - 1) Dry process
 - 2) Excellent particle removal performance
- **Disadvantages**
 - 1) Pattern damage => flat surface
 - 2) Thermal shock
 - 3) Expensive maintenance due to high purity Ar
 - 4) Expensive equipment due to Vacuum process

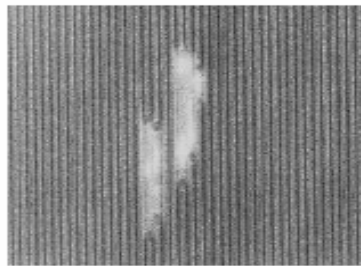
Ar aerosol cleaning (2)

■ Cleaning performance

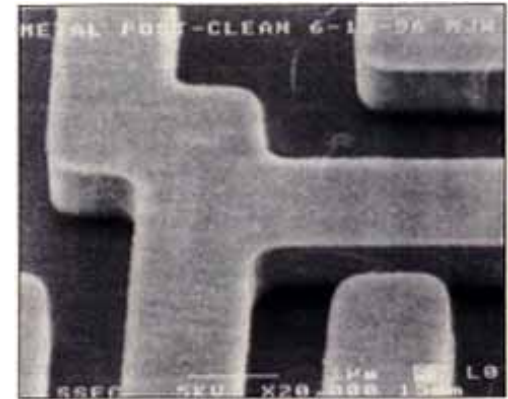
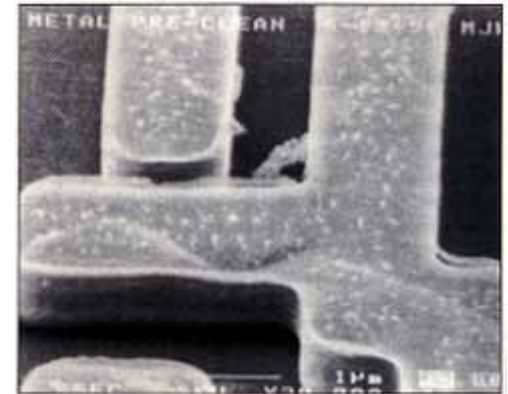
	Before cleaning	After cleaning	Efficiency
SiO ₂ slurry on oxide	 Above 30000ea	 75ea	≃ 99%
Si ₃ N ₄ particle on bare	 Above 30000ea	 301ea	≃ 99%



Accel. N₂ = 0l/min
(0.15 μm poly line)



Accel. N₂ = 15l/min
(0.15 μm poly line)

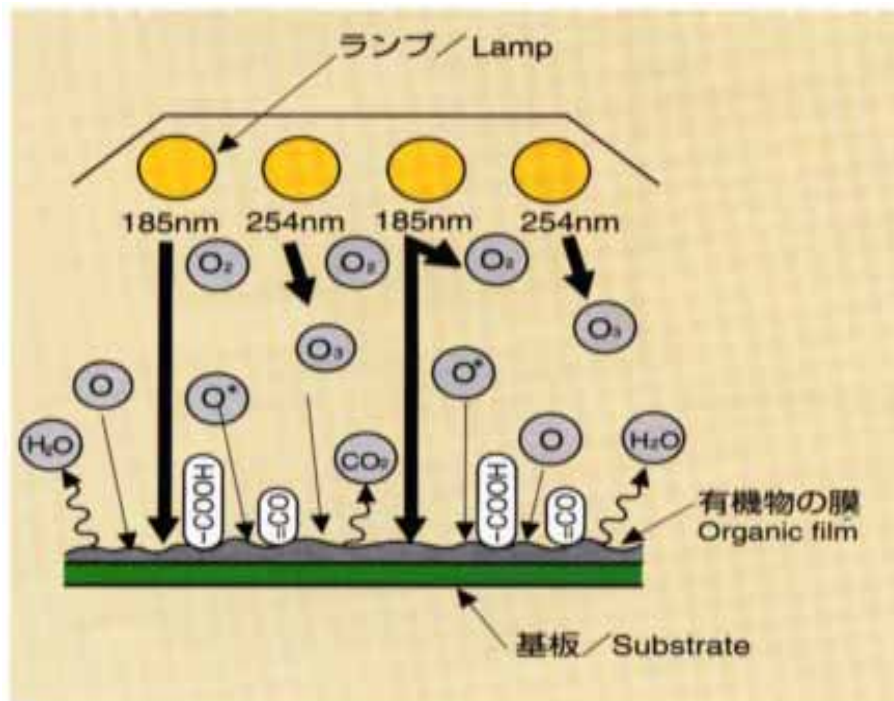


Corrosion removal
on Al line

UV lamp cleaning

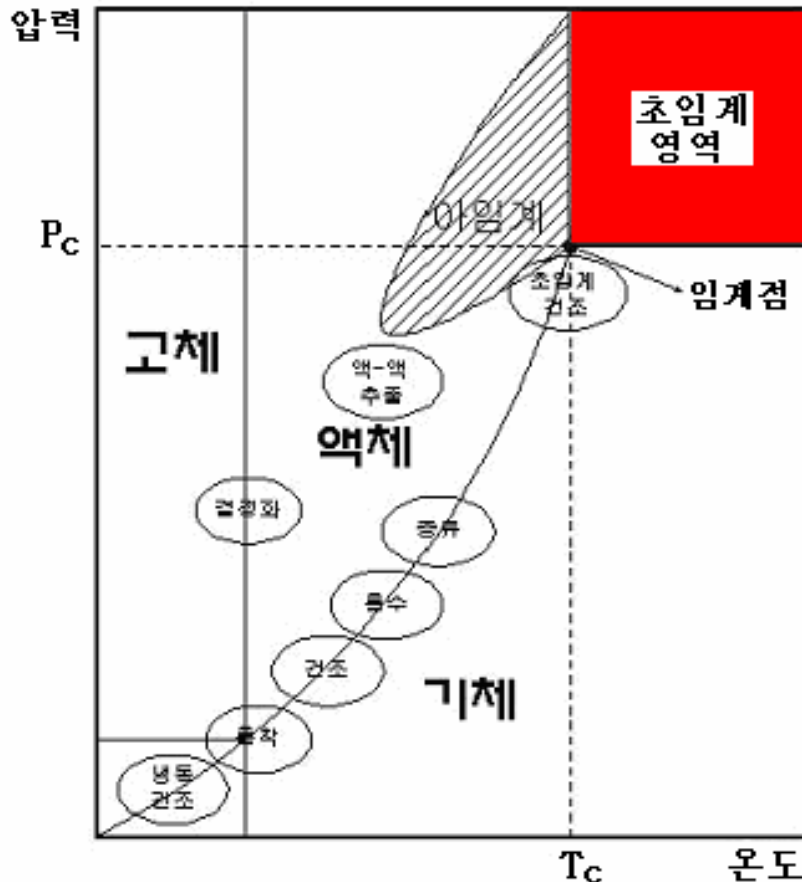
- UV radiation (Hg lamp) + O₂ => O & O₃ (O+O₂)
- Mechanisms: Direct bond breaking + Chemical reaction
- $E = h\nu = hc/\lambda$
- Organic contamination removal (UV/O₃ cleaning)
- Applications: PR hardening, OELD cleaning, surface activation

>> Competition with AP tech



Super critical fluid cleaning (1)

■ Super critical region



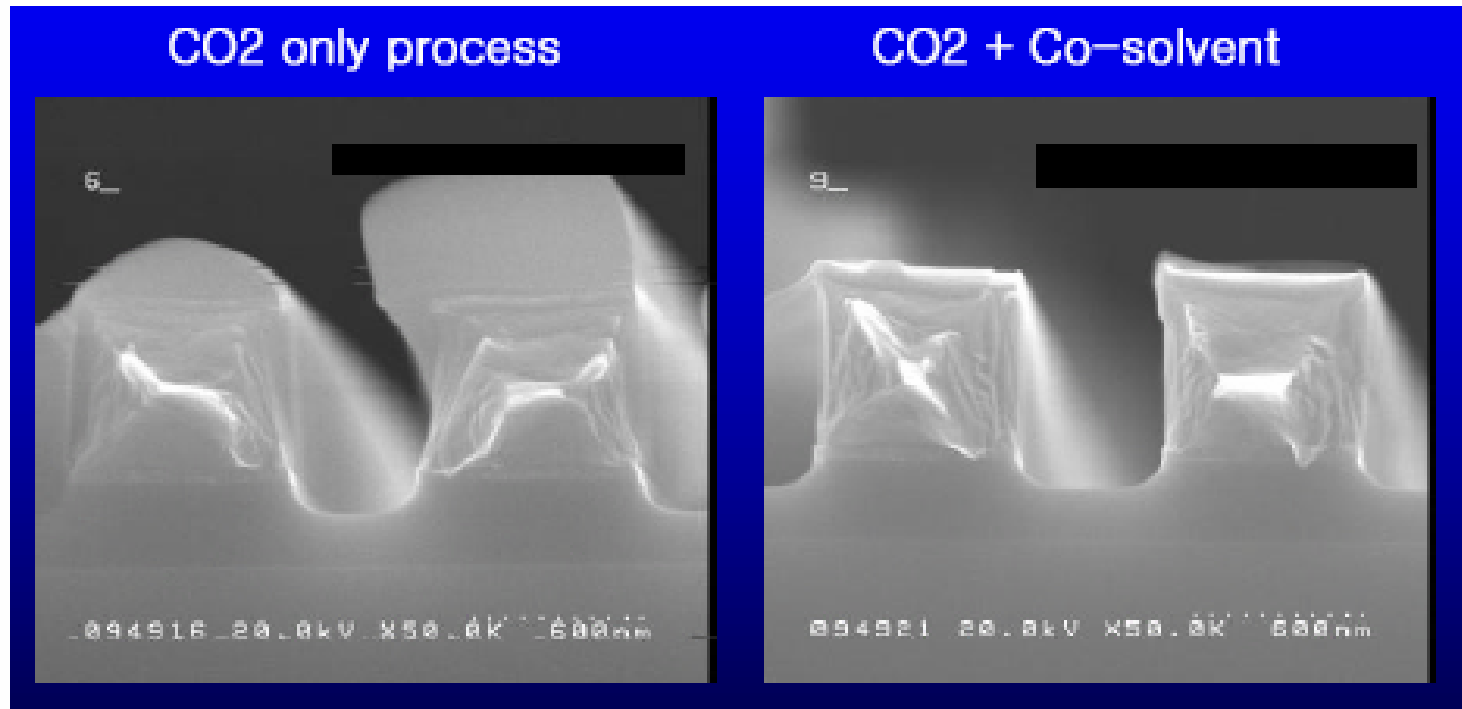
- SCF characteristics (CO₂)
 - > High density (~liquid)
 - > Low viscosity (~gas)
 - > High diffusivity (~gas)
 - > High solubility (CO₂)
 - > Easy recycling

- Organic removal process
 - > PR removal

- Nano-scale pattern rinse & dry process
 - > Deep penetration

Super critical fluid cleaning (2)

- SCF Cleaning Demonstration



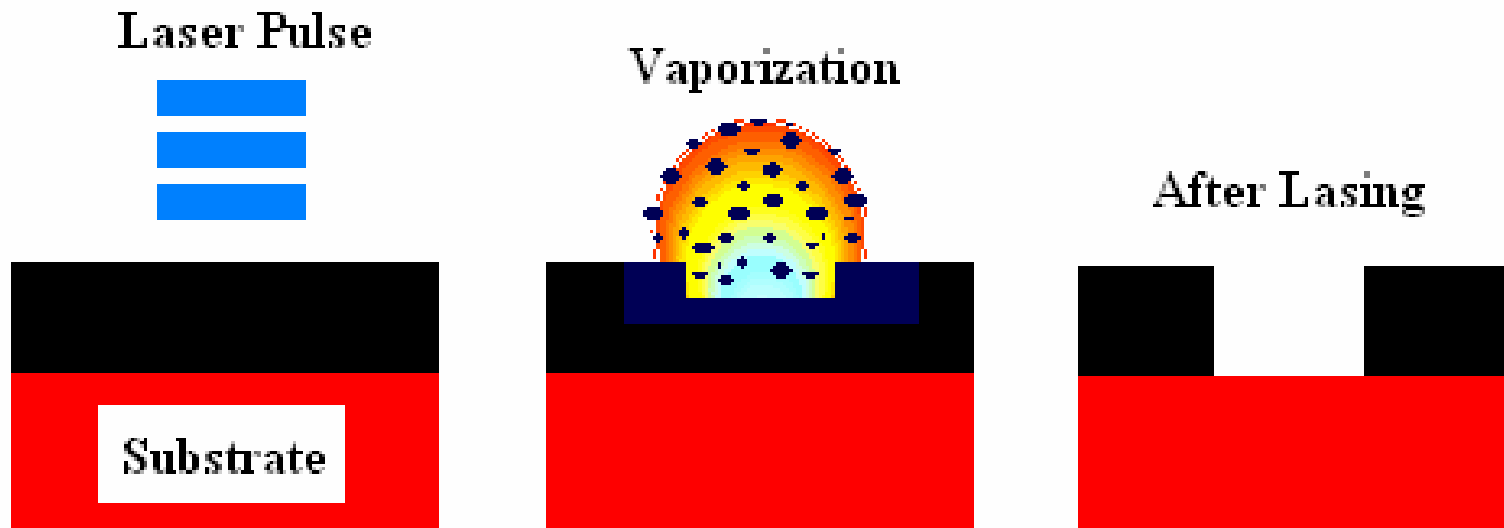
Source: K.T.Lee at Surface cleaning workshop, Boston

>> **Co-solvent** is essential to enhance the cleaning performance.

What is a laser cleaning?

- **Definition of laser cleaning**

: A process which removes contaminants from a surface by laser-surface interactions



- **Cleaning mechanisms**

1. Photo-thermal effect
2. Photo-mechanical effect
3. Photo-chemical effect

*Ref: 가 ,
, 2002*



Process characteristics

- **Unique characteristics**

- Precise process which ceases shortly after the laser pulse has ended
- Selective process which can be tuned for the removal of specific substances with a proper selection of wavelength
- Non-contact process which produces no contact wear
- Surface relief process without any mechanical loads
- Controllable process that a specific thickness of materials can be removed
- Environmentally preferable (or clean) process since it is a dry process

Artwork conservation



(a) Initial appearance after excavation

First laser cleaning shoot at 1975, Venice



(b) After initial laser cleaning



(c) After completion of laser cleaning



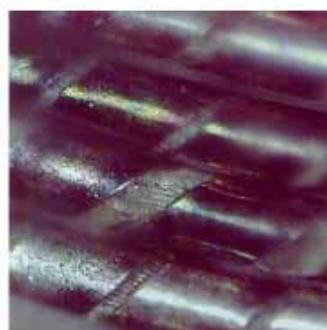
19C Swedish Royal Silver Textile



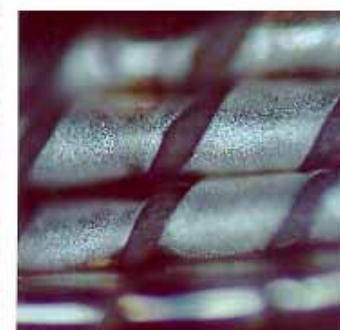
(a) Before laser cleaning



(b) After laser cleaning



Before cleaning



After laser cleaning



Medical applications

*** Applications: Dermatology & Dental Surgery



Before treatment



After treatment



Before treatment



After treatment



Before treatment



After treatment



Before treatment



After treatment

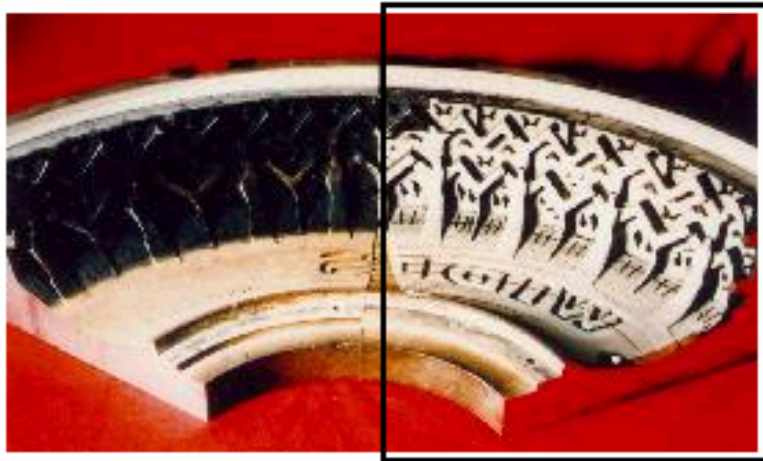


Before treatment



After treatment

Industrial applications

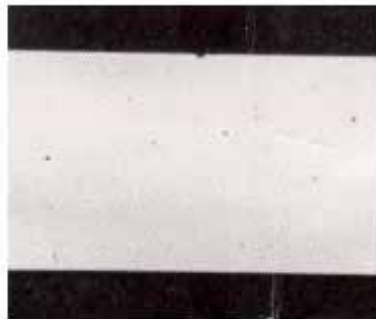


Uncleaned area

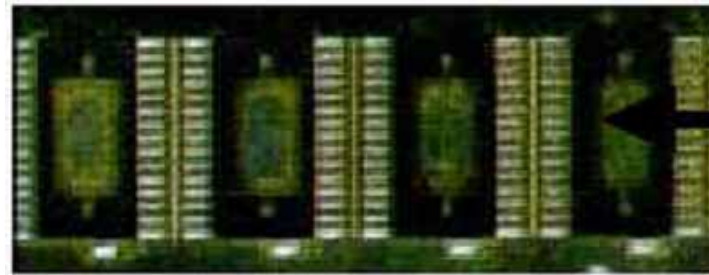
Cleaned area



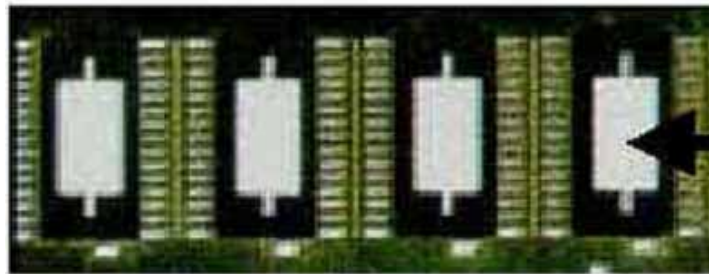
Before laser cleaning



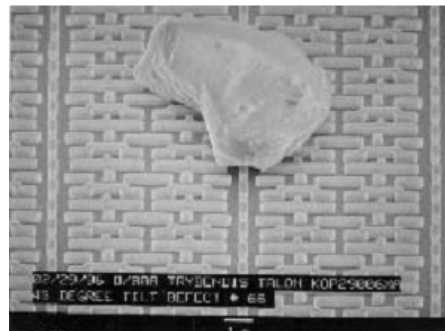
After laser cleaning



Flash on
Heat sink



Heat sink



Before cleaning



After cleaning

Comparison of cleaning processes

	Media blasting	Dry ice cleaning	Wet chemical cleaning	Laser cleaning
In-situ cleaning (op. Off-line)	No	Yes	No	Yes
Labor required	High	Medium	High	Low
Level of automation	Low	Low	Low	High
Noise level	Medium	High	Low	Low
Substrate wear	Yes	No	Medium	No
Environmental hazards	Medium	Medium	High	Low
Post-cleaning waste	High	Low	High	Low



Summary

- Every cleaning methodologies have **their own advantages and drawbacks**, so fundamental understanding of the cleaning processes is most important for successful applications.
- Cleaning prospect (Semi. Industry)
 - > **Wet & Batch => Hybrid => Dry & Single**
- **Laser cleaning** has unique characteristics and its industrial applications will be expand rapidly.
- iMT holds diverse laser cleaning techniques and systems, i.e. **LSC, LPC, SLC, LMC, ISM** etc.
- A **creative idea from industrial fields** is most important to implement the new technology successfully.